MSKSEMI 美森科







TVS



TSS



MOV



GDT



DIED

PESD0603MS07-MS

Product specification





FEATURES

- Ultra-Low capacitance:0.05pF(typ.)
- Low leakage current(<100nA)
- Fast response time(<1ns)
- Bi-directional, single line protection
- IEC 61000-4-2 (ESD Air): 15kV

IEC 61000-4-2 (ESD Contact): 8kV

Applications

- USB 3.0/3. 1
- HDMI 1.3/ 1.4/2.0
- RF Antenna
- SATA and eSATA Interface

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION
0603	



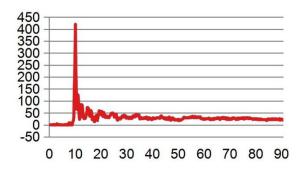
Limiting Values(TA = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
Fleetrestatic Discharge Veltage		IEC 61000-4-2; Contact Discharge	-	8	kV
V _{ESD} Electrostatic Discharge Voltage	IEC 61000-4-2; Air Discharge	-	15	kV	
TA	Operating Temperature Range	-	-40	90	°C
Tstg	Storage Temperature Range	-	-55	125	°C

ELECTRICAL CHARACTERISTICS (Tamb=25℃)

Symbol	Parameter	Conditions	Min	Тур.	Max	Unit
Vdc	Continuous Operating Voltage	-	-	-	7	V
VT	Trigger Voltage	IEC61000-4-2 8kV contact discharge	-	450	-	V
Vc	Clamping Voltage	IEC61000-4-2 8kV contact discharge	-	40	-	V
lι	Leakage Current	DC 7V shall be applied on component	-	-	100	nA
Сл	Capacitance	Measured at 10 MHz	_	0.05	-	pF





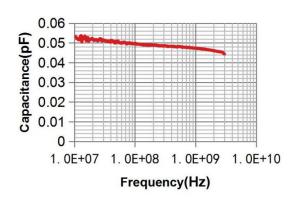


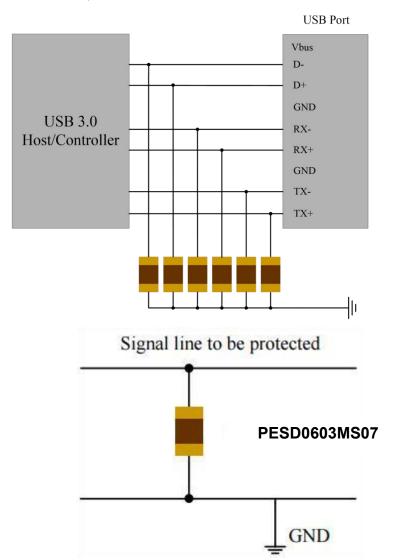
Fig. 1 Typical ESD Response (IEC 61000-4-2, 8kV contact discharge)

Fig.2 Typical Device Capacitance VS. Frequency

ESD Protection for Signal Line

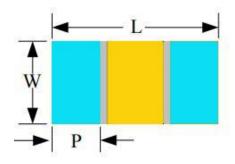
The PESD is designed for the protection of one bidirectional data line from ESD damage.

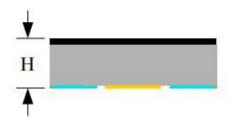
- Place the PESD as close to the input terminal or connector as possible.
- Minimize the path length between the PESD and the protected signal line.
- Use ground planes whenever possible.



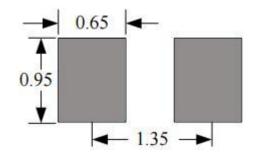


PACKAGE MECHANICAL DATA





Recommended Solder Pad Footprint



ONotes:

This solder pad layout is for reference purposes only.

Dimension	Unit: Millimeters		
	Min	Max	
L	1.45	1.75	
W	0.70	0.95	
Р	0.20	0.50	
Н	0.26	0.46	

REEL SPECIFICATION

P/N	PKG	QTY
PESD0603MS07-MS	0603	5000



Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer'sproducts or equipment.
- MSKSEMI Semiconductor. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with someprobability. It is possiblethat these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits anderror prevention circuitsfor safedesign, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from theauthorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. Whendesigning equipment, referto the "Delivery Specification" for the MSKSEMI Semiconductor productthat you intend to use.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for ESD Suppressors / TVS Diodes category:

Click to view products by MSKSEMI manufacturer:

Other Similar products are found below:

60KS200C D18V0L1B2LP-7B D5V0F4U5P5-7 NTE4902 P4KE27CA P6KE11CA P6KE8.2A SA60CA SA64CA SMBJ12CATR
SMBJ33CATR SMBJ6.5A SMBJ8.0A ESD101-B1-02ELS E6327 ESD112-B1-02EL E6327 ESD7451N2T5G 19180-510 CPDT-5V0USP-HF 3.0SMCJ33CA-F 3.0SMCJ36A-F HSPC16701B02TP JANTX1N6126A D3V3Q1B2DLP3-7 D55V0M1B2WS-7 SCM1293A-04SO
ESD200-B1-CSP0201 E6327 SM12-7 CEN955 W/DATA VESD12A1A-HD1-GS08 CPDQC5V0-HF D1213A-01LP4-7B ESD101-B1-02EL
E6327 AOZ8808DI-03 5KP15A 5KP48A 5KP90A ESD3V3D7-TP 15KPA36A-LF P4KE56CA P4KE68A P4KE91CATR P6KE120A
P6KE13CA P6KE43CA P6KE6.8CA P6KE8.2 P6SMBJ20CA JANTX1N6072A SR2835ESKG SA90CA